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AMENDMENTS TO THE SPECIFICATION

Please amend the specification by substituting the following replacement paragraphs.

[0042] Within the preferred embodiment of the present invention, the conductor passivation layer 17 is formed of a noble metal conductor passivation material selected from the group consisting of gold, gold alloys, palladium, palladium alloys, platinum, nickel platinum alloys (the alloys having a base noble metal content of at least about 90 weight percent and more typically and preferably from about 90 to about 95 weight percent). Within the present invention and the preferred embodiment of the present invention, gold and gold alloys are particularly preferred for forming the conductor passivation layer 17. Typically and preferably, the conductor passivation layer 17 is formed to a thickness of from about 9000 to about 12000 angstroms, while employing, if feasible, an electroless plating method as is otherwise generally conventional in the art of microelectronic fabrication. As is illustrated within Fig. 3, the conductor passivation layer 17 is formed aligned upon the bond pad 15 and contained within the linewidth of the bond pad 15.

[0045] Shown in Fig. 4 is a schematic cross-sectional diagram of a color filter sensor image array optoelectronic microelectronic fabrication otherwise equivalent to the color filter sensor image array optoelectronic microelectronic fabrication whose schematic cross-sectional diagram is illustrated in Fig. 3, but wherein there is formed upon a portion of the etched blanket dielectric passivation layer 16' over the active region R1 of the substrate 10 but not the peripheral region R1 R2 of the substrate 10, a series of layers comprising: (1) a planarizing layer 18 formed upon the etched blanket dielectric passivation layer 16'; (2) a color filter layer 20 formed upon the planarizing layer 18; (3) a spacer layer 22 formed upon the color filter layer 20; and (4) a

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series of microlens layers 24a, 24b and 24c formed upon the spacer layer 22 and registered with the individual photoactive regions 12a, 12b and 12c within the active region R1 of the substrate 10.